L Number	Hits	Search Text	DB	Time stamp
-	43	("6232147" "6455408" "5910644" "6501165" "6620633" "6620731" "5792594" "6218281" "5567981" "6388333" "6064112" "6403457" "6232147" "6335104" "6355104" "6396148" "6303424" "6372624" "6380555" "6127736" "6451624" "6303524").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 10:28
-	1362	(bond or bonding or wirebond or stud near2 bump or solder near2 ball or ball near2 grid) near10 (nickel or vanadium or chromium or copper or ni or v or cr or cu or crcu) near10 (gold or au or platinum or pt or palladium or pd or non-oxidizing or nonoxidizing) same (redistribution or redistributing or trace or lead or path)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 15:30
-	205	(bond or bonding or wirebond or stud near2 bump or solder near2 ball or ball near2 grid) near8 (nickel or vanadium or chromium or copper or ni or v or cr or cu or crcu) near8 (gold or au or platinum or pt or palladium or pd or non-oxidizing or nonoxidizing) same (redistribution or redistributing or trace)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 16:09
-	22	("3761782" | "4074342" | "4670770" | "4709468" | "4829014" | "4890157" | "4948754" | "5106461" | "5137845" | "5198684" | "5219117" | "5224265" | "5246880" | "5327013" | "5404265" | "5436411" | "5502002" | "5505366" | "5604379" | "5677576" | "5719448" | "5851911").PN.	USPAT	2004/04/14 15:43
-	228	(redistribution or redistributing) same (wirebond or wirebonding or wire adj bond or wire adj bonding or solder adj ball or conductive adj ball or ball adj grid or solder adj bump or conductive adj bump) with (pad or electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 16:35
-	0	(redistribution or redistributing) near3 (stack or laminate or laminated) same (wirebond or wirebonding or wire adj bond or wire adj bonding or solder adj ball or conductive adj ball or ball adj grid or solder adj bump or conductive adj bump) with (pad or electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 15:02
-	14	(redistribution or redistributing) near3 (stack or laminate or laminated) and (wirebond or wirebonding or wire adj bond or wire adj bonding or solder adj ball or conductive adj ball or ball adj grid or solder adj bump or conductive adj bump) with (pad or electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 15:04
-	130	non-oxidizing near2 (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 16:33
-	2	6492198.URPN.	USPAT	2004/04/16 11:03
-	0	(nonoxidizing or non-oxidizing or wettable) near6 (gold or au) near6 electroless$ and (barrier or ubm) near6 (nickel or ni) near6 electroless$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 16:34
-	34	(wirebond or wirebonding or wire adj bond or wire adj bonding or solder adj ball or conductive adj ball or ball adj grid or solder adj bump or conductive adj bump) near6 (pad or electrode) near10 (barrier or ubm) and (barrier or ubm or nickel) near6 (electroless$ or electro-less$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 16:39

-	45	(wirebond or wirebonding or wire adj bond or wire adj bonding or solder adj ball or conductive adj ball or ball adj grid or solder adj bump or conductive adj bump) near6 (pad or electrode) near10 (barrier or ubm) and (barrier or ubm or nickel or ni or gold or au or wettable or non-oxidizing or nonoxidizing) near6 (electroless$ or electro-less$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 16:41